

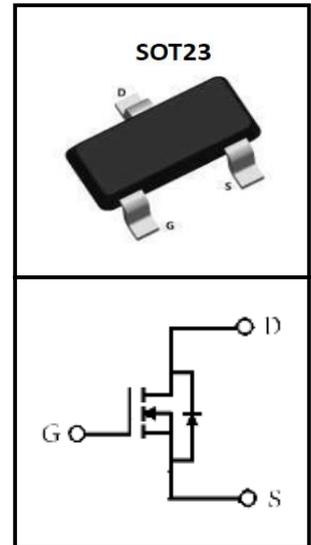
20V N-Channel Trench MOSFET

FEATURES

- Super Low Gate Charge
- 100% EAS Guaranteed
- RoHS compliant
- Green Device Available
- Excellent CdV/dt effect decline
- Advanced high cell density Trench technology

APPLICATIONS

- Switch Mode Power Supply (SMPS)
- Uninterruptible Power Supply (UPS)
- Power Factor Correction (PFC)



Device Marking and Package Information

Device	Package	Marking
CTZ2312A	SOT-23	2312A

Absolute Maximum Ratings at $T_J = 25^\circ\text{C}$ unless otherwise noted

Parameter	Symbol	Value	Unit
Drain-Source Voltage ($V_{GS} = 0V$)	V_{DSS}	20	V
Drain Current-Continuous($T_C = 25^\circ\text{C}$)	I_D	5	A
Drain Current-Continuous($T_C = 100^\circ\text{C}$)		4	
Pulsed Drain Current	I_{DM}	20	A
Gate Source Voltage	V_{GSS}	± 12	V
Single Pulse Avalanche Energy	E_{AS}	15	mJ
Avalanche Current	I_{AS}	10	A
Power Dissipation $T_C = 25^\circ\text{C}$	P_D	1.56	W
Power Dissipation $T_C = 100^\circ\text{C}$		0.62	
Operating Junction and Storage Temperature Range	T_J, T_{stg}	-55~+175	$^\circ\text{C}$

Thermal Characteristics

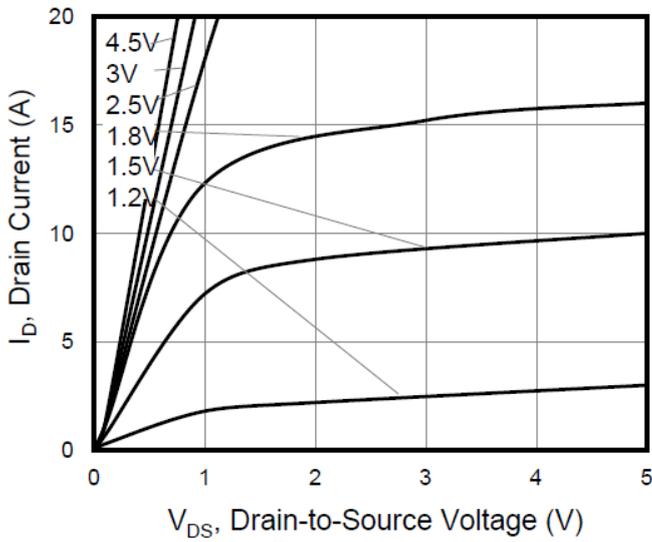
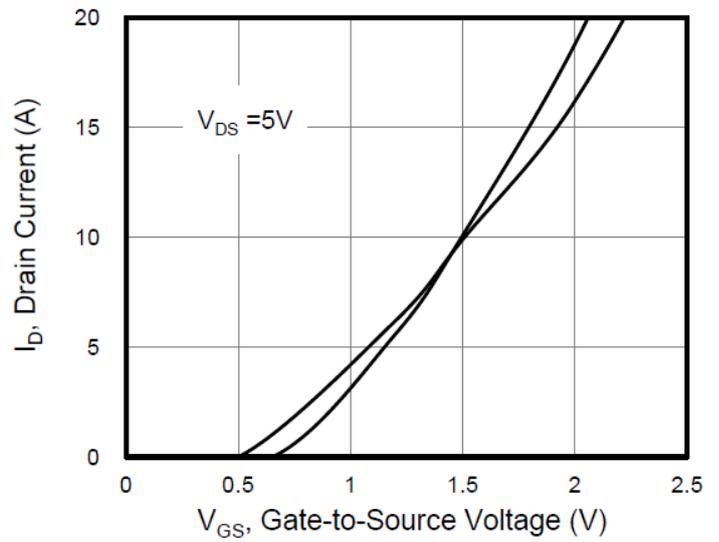
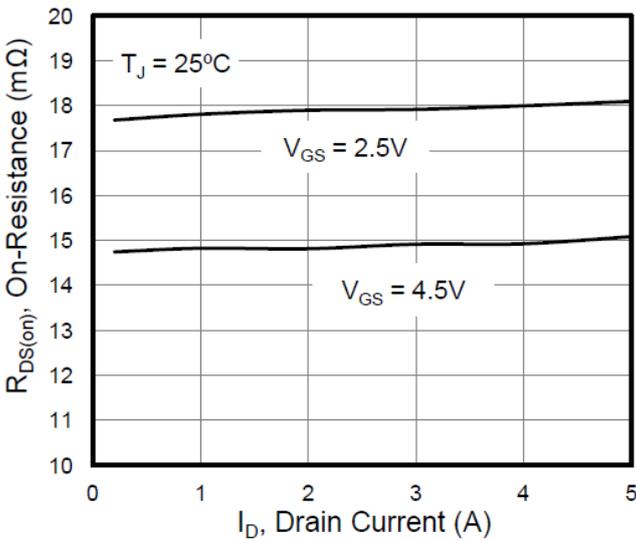
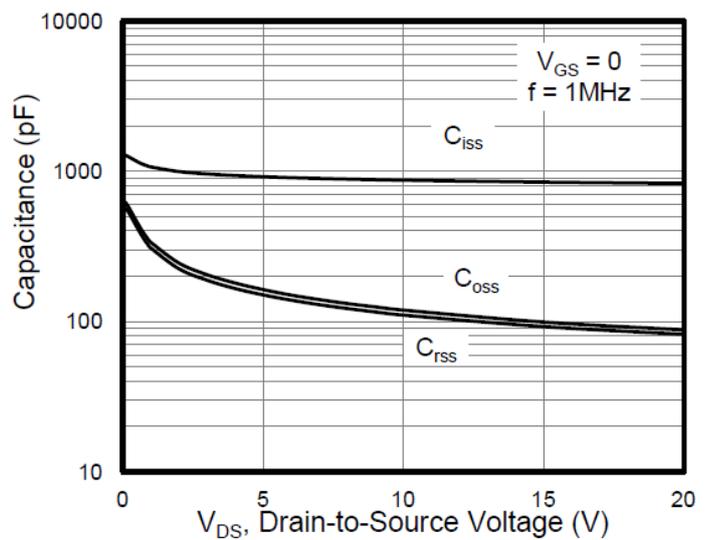
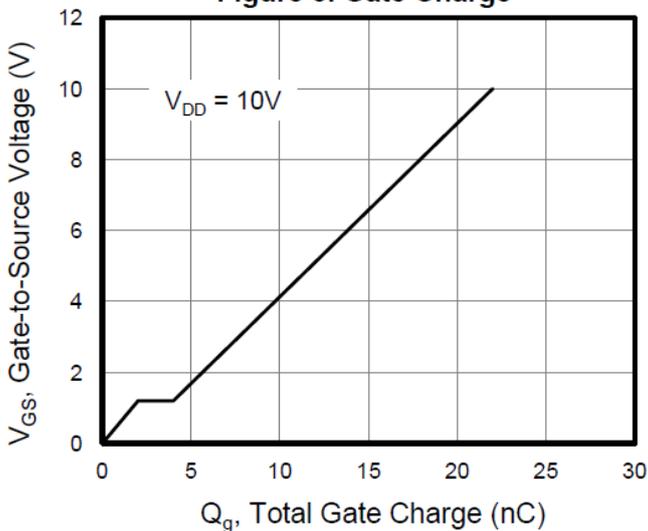
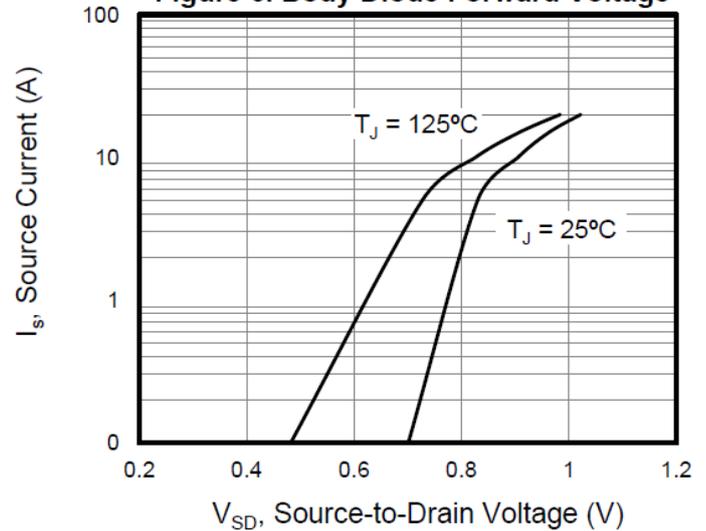
Parameter	Symbol	Value	Unit
Thermal Resistance, Junction-to-Case (note1)	$R_{\theta JC}$	80	$^\circ\text{C/W}$
Thermal Resistance, Junction-to-Ambient (note1)	$R_{\theta JA}$	125	$^\circ\text{C/W}$

Electrical Characteristics $T_J = 25^\circ\text{C}$ unless otherwise specified							
Parameter	Symbol	Test Conditions	Value			Unit	
			Min.	Typ.	Max.		
Static							
Drain-Source Breakdown Voltage	$V_{(BR)DSS}$	$V_{GS} = 0V, I_D = 250\mu A$	20	--	--	V	
Zero Gate Voltage Drain Current	I_{DSS}	$V_{DS} = 20V, V_{GS} = 0V, T_J = 25^\circ\text{C}$	--	--	1	uA	
Zero Gate Voltage Drain Current	I_{DSS}	$V_{DS} = 20V, V_{GS} = 0V, T_J = 100^\circ\text{C}$	--	--	25		
Gate-Source Leakage	I_{GSS}	$V_{GS} = \pm 12V$	--	--	± 100	nA	
Gate-Source Threshold Voltage	$V_{GS(th)}$	$V_{DS} = V_{GS}, I_D = 250\mu A$	0.5	0.7	0.9	V	
Drain-Source On-Resistance (note2)	$R_{DS(on)}$	$V_{GS} = 10V, I_D = 4A$	--	13.6	18	m Ω	
		$V_{GS} = 4.5V, I_D = 4A$	--	14.9	20	m Ω	
		$V_{GS} = 2.5V, I_D = 4A$	--	18	25	m Ω	
Forward Transconductance (note2)	gfs	$V_{GS} = 5V, I_D = 6A$	--	25	--	s	
Dynamic							
Input Capacitance	C_{iss}	$V_{GS} = 0V, V_{DS} = 10V, f = 1.0MHz$	--	870	--	pF	
Output Capacitance	C_{oss}		--	119	--		
Reverse Transfer Capacitance	C_{rss}		--	110	--		
Total Gate Charge (10V)	Q_g	$V_{DS} = 10V, I_D = 5A, V_{GS} = 10V$	--	22.1	--	nC	
Total Gate Charge (4.5V)			--	11	--		
Gate-Source Charge			Q_{gs}	--	2		--
Gate-Drain Charge			Q_{gd}	--	2		--
Turn-on Delay Time	$t_{d(on)}$	$V_{DS} = 10V, V_{GS} = 10V, I_D = 3A, R_G = 2.5\Omega$	--	4	--	ns	
Turn-on Rise Time	t_r		--	8.2	--		
Turn-off Delay Time	$t_{d(off)}$		--	22	--		
Turn-off Fall Time	t_f		--	7	--		
Body Diode Characteristics							
Continuous Body Diode Current	I_{SD}	$T_C = 25^\circ\text{C}$	--	--	5	A	
Pulsed Diode Forward Current	I_{SM}		--	--	20		
Body Diode Voltage	V_{SD}	$T_J = 25^\circ\text{C}, I_{SD} = 5A, V_{GS} = 0V$	--	--	1.2	V	

Notes

- 1.Repetitive Rating: Pulse Width limited by maximum junction temperature
- 2.VDD = 20V, RG = 25 Ω , Starting TJ = 25 $^\circ\text{C}$
- 3.Pulse Test: Pulse Width $\leq 300\mu\text{s}$, Duty Cycle $\leq 1\%$

Typical Characteristics $T_J = 25^\circ\text{C}$, unless otherwise noted

Figure 1. Output Characteristics

Figure 2. Transfer Characteristics

Figure 3. On-Resistance vs. Drain Current

Figure 4. Capacitance

Figure 5. Gate Charge

Figure 6. Body Diode Forward Voltage


Typical Characteristics $T_J = 25^\circ\text{C}$, unless otherwise noted

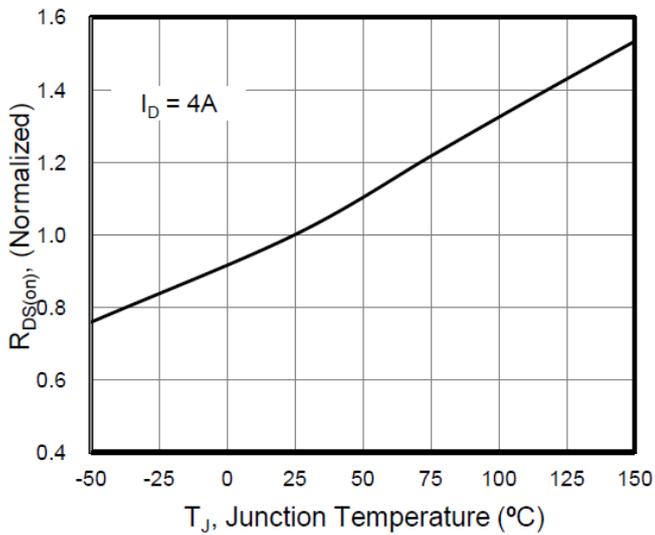
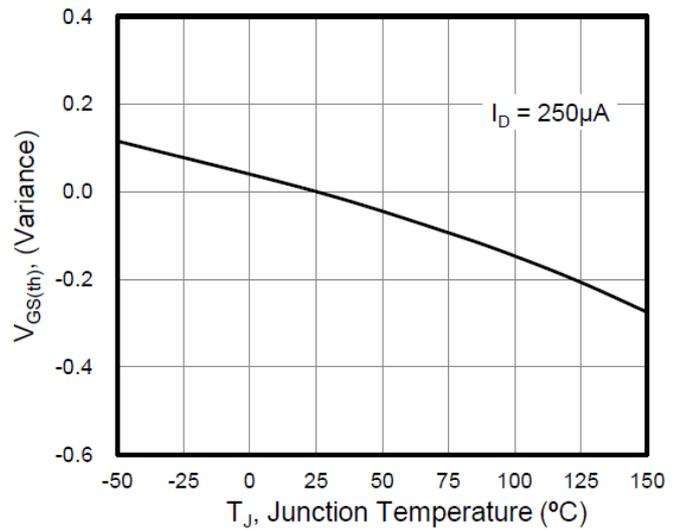
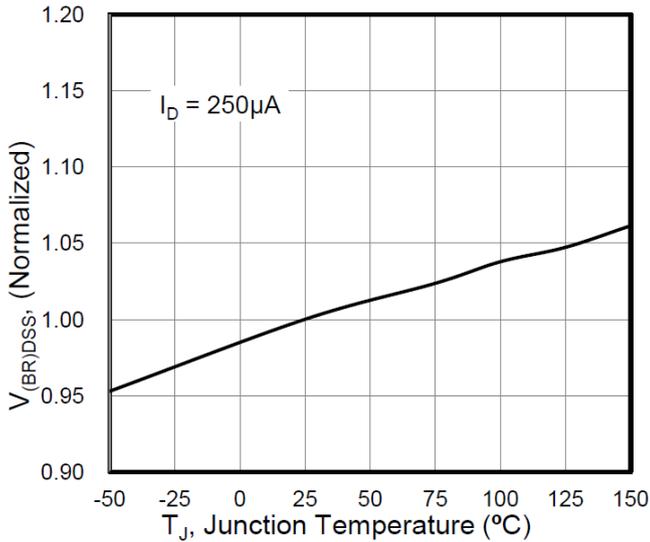
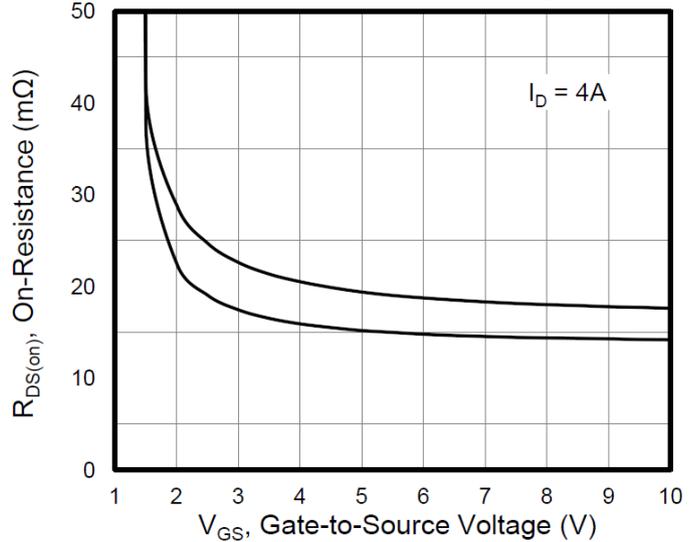
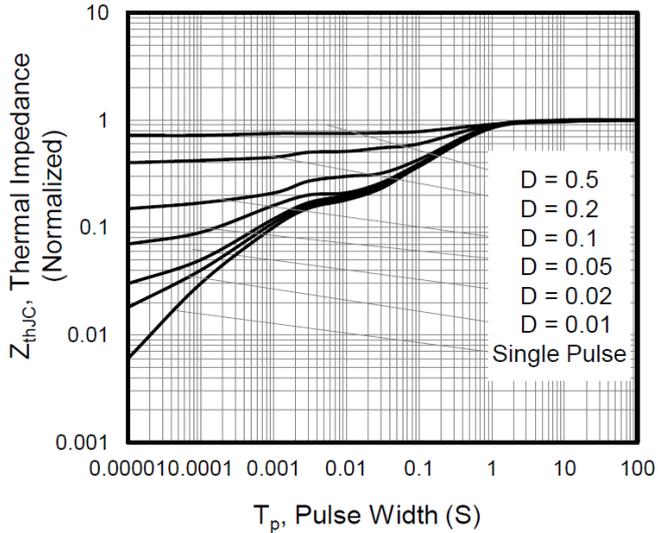
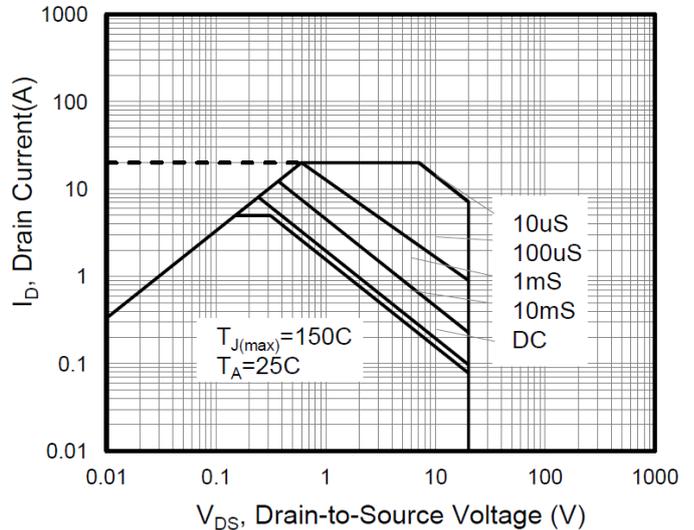
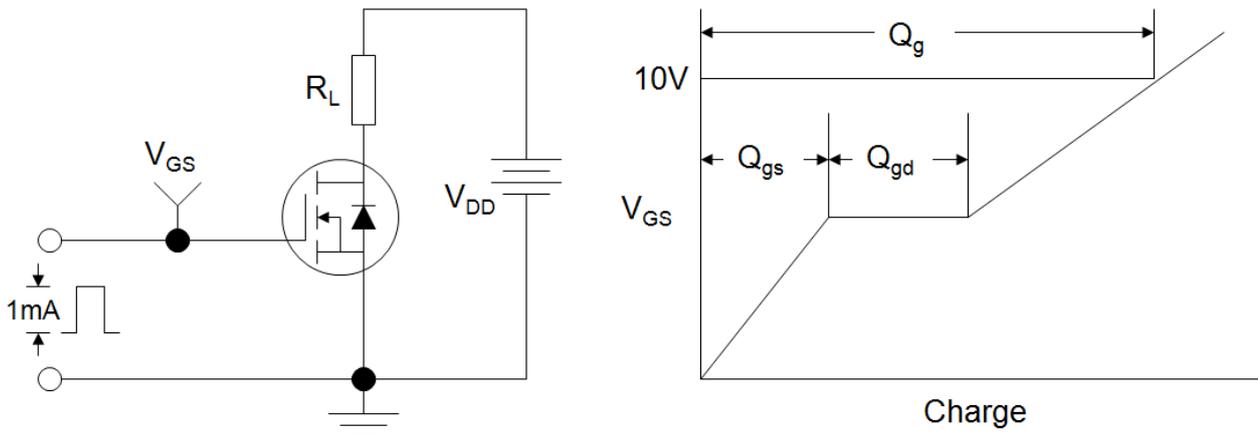
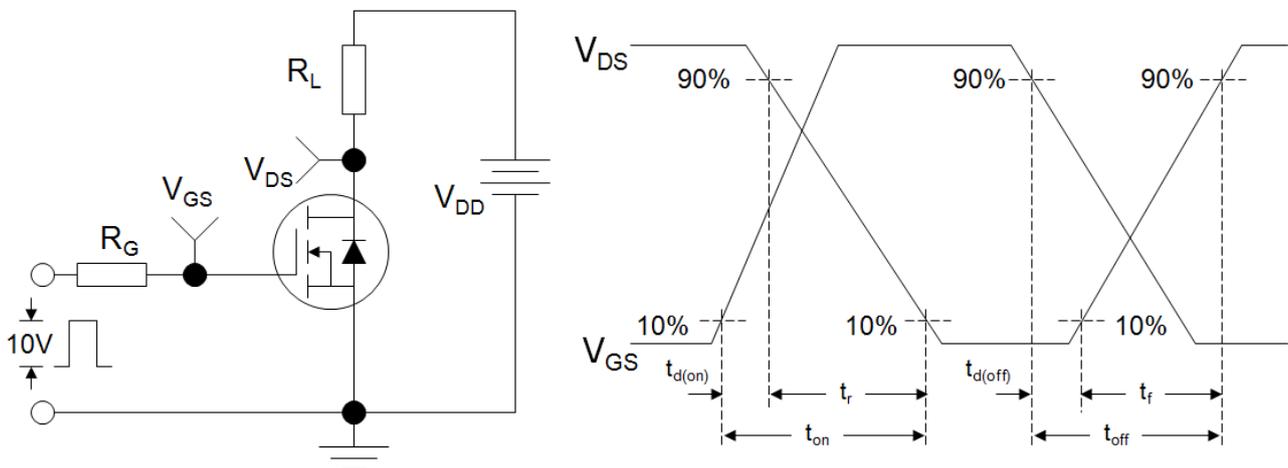
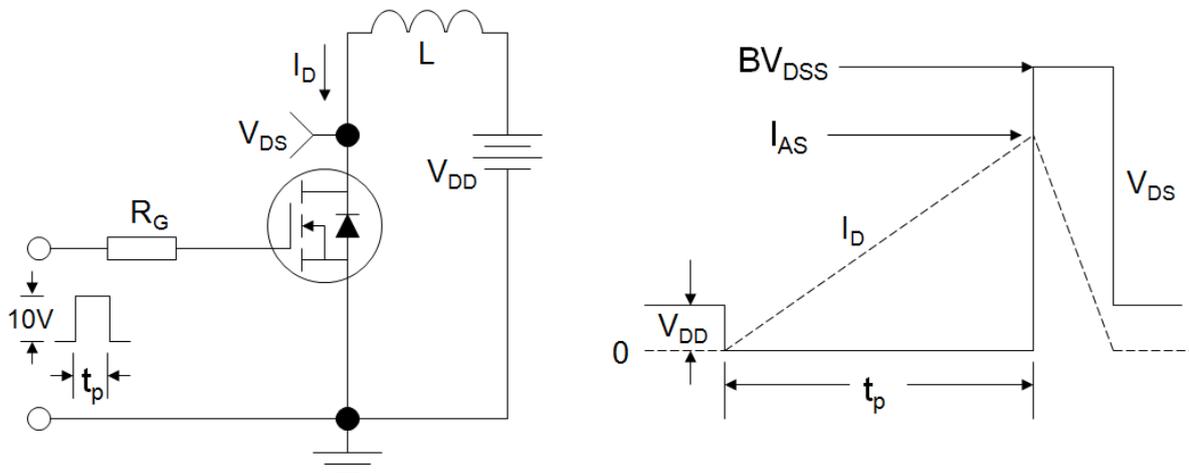
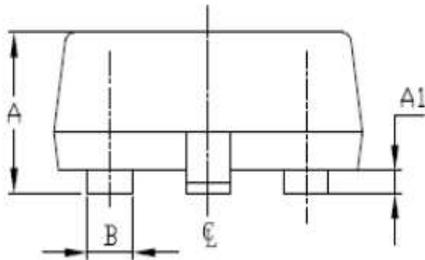
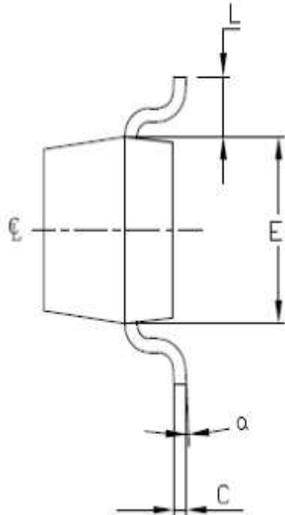
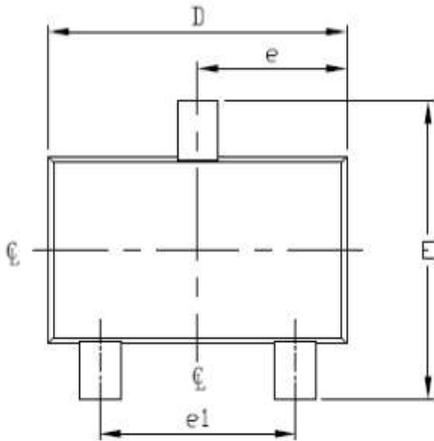
Figure 7. On-Resistance vs. Junction Temperature

Figure 8. Threshold Voltage vs. Junction Temperature

Figure 9. V(BR)DSS vs. Junction Temperature

Figure 10. On-Resistance vs. Gate-to-Source Voltage

Figure 11. Transient Thermal Impedance

Figure 12. Safe operation area


Figure A: Gate Charge Test Circuit and Waveform

Figure B: Resistive Switching Test Circuit and Waveform

Figure C: Unclamped Inductive Switching Test Circuit and Waveform


SOT23



COMMON DIMENSIONS			
SYMBOL	mm		
	MIN	NOM	MAX
A	0.9	1.0	1.1
A1	0.00	0.06	0.1
B	0.3	0.4	0.5
C	0.07	0.09	0.18
D	2.8	2.9	3.04
E	2.1	2.33	2.64
E1	1.2	1.3	1.4
e	1.4	1.45	1.5
e1	1.80	1.90	2.00
L	0.45	0.54	0.63
α	0°	2.5°	7°

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